What is claimed is:

1. A multi-station glue dispenser, comprising:

a loading and unloading mechanism defining a motion space therein, a plurality of processing stations being provided at a peripheral of the loading and unloading mechanism, the loading and unloading mechanism being configured to move between the motion space and each of the plurality of processing stations to transport a wafer, and the plurality of processing stations comprising a positioning station, a preheating station and a plurality of glue dispensing stations;

a wafer scanning and positioning mechanism located at the positioning station and configured to scan and position the wafer transported by the loading and unloading mechanism;

a wafer preheating mechanism located at the preheating station and configured to preheat the wafer transported by the loading and unloading mechanism;

a wafer heating mechanism located at the glue dispensing station and configured to heat the wafer in the processing station; and

a glue dispensing mechanism fitting with the wafer heating mechanism to dispense glue on the heated wafer.

2. The multi-station glue dispenser of claim 1, wherein the loading and unloading mechanism comprises:

a loading and unloading body defining the motion space therein, the loading and unloading body being provided with two ports that are respectively located at both ends of the loading and unloading body, the two ports being in communication with the motion space, and at least two processing stations being provided at each of both sides of the loading and unloading body;

a movable element provided in the motion space and movable between the two ports; and

a material taking machine provided on the movable element to pick up a wafer from the port or the processing station, or to place a wafer onto the port or the processing station.

3. The multi-station glue dispenser of claim 2, wherein the loading and unloading body is in a shape of "⊐" with an opening facing upward, each of a plurality of supporting legs of the loading and unloading body is provided with the port, and the loading and unloading mechanism further comprises:

two cartridges which are respectively provided on the positions corresponding to the ports on two support legs, and at least a portion of the material taking machine being configured to extend out of the port and into the cartridge to load and unload a wafer.

4. The multi-station glue dispenser of claim 2 or 3, wherein the loading and unloading mechanism further comprises a loading and unloading transmission mechanism, the loading and

unloading transmission mechanism being provided between the two ports and being movable between the two ports to drive the movable element to move, and the loading and unloading transmission mechanism comprises:

a side panel extending within the loading and unloading body along a lengthwise direction of the loading and unloading body, the side panel having a mounting surface at a lateral side thereof;

a transmission rail disposed on the mounting surface and extending along the lengthwise direction of the loading and unloading body, the movable element being movably provided on the transmission rail; and

a loading and unloading driving element provided on the mounting surface and connected with the movable element to drive the movable element to move.

5. The multi-station glue dispenser of any of claims 1 to 4, wherein the wafer scanning and positioning mechanism is provided between two adjacent glue dispensing stations, and the wafer scanning and positioning mechanism comprises:

a scanning member configured to scan and identify the wafer; and

an positioning member configured to position the wafer transported by the loading and unloading mechanism to adjust the position of the wafer.

6. The multi-station glue dispenser of any of claims 1 to 5, wherein the wafer preheating mechanism and the wafer heating mechanism comprise:

a base;

a heater provided on the base, an upper surface of the heater being configured as a heating surface; and

a lifting assembly provided on the base and movable between an ascending state and a non-ascending state, the lifting assembly being configured to support a wafer to allow the wafer to be spaced apart from the heating surface when the lifting assembly is in the ascending state and being configured to allow the wafer to be in contact with the heating surface when the lifting assembly is in the non-ascending state;

wherein the heater is configured to heat the wafer in a non-contact way to allow the temperature of the wafer to raise gradually during the lifting assembly transits gradually from the ascending state to the non- ascending state.

7. The multi-station glue dispenser of claim 6, wherein, the base comprises:

a base board;

a plurality of supporting rods provided on the base board; and

a heater supporting platform provided on the plurality of supporting rods and spaced apart from the base board, and both the heater and the lifting assembly being provided on the heater supporting

platform.

8. The multi-station glue dispenser of claim 7, wherein the heating surface has at least two heating regions for heating wafers of different sizes, each of the at least two heating regions has at least one vacuum absorption hole, and the wafer preheating mechanism further comprises:

a vacuum absorption member in communication with the vacuum absorption hole to fix the wafer when the wafer is one the heater.

9. The multi-station glue dispenser of any of claims 1 to 8, wherein the glue dispensing mechanism comprises:

a glue dispensing body;

a glue dispensing head assembly movably provided on the glue dispensing head assembly and located above the wafer heating mechanism to dispense glue onto the wafer placed on the wafer heating mechanism; and

a static charge dissipating member movably provided on the glue dispensing body and located above the wafer heating mechanism to dissipate static charges on the wafer heating mechanism and the wafer.

10. The multi-station glue dispenser of claim 9, wherein the glue dispensing mechanism further comprises:.

a mounting frame provided on the glue dispensing body;

a barrel provided on the mounting frame and infused with glue; and

a liquid level detecting member provided on the barrel and/or the mounting frame to determine the liquid level of the glue in the barrel based on an optical signal or sensed signal regarding the liquid level of the glue in the barrel.

11. A glue dispensing method of the multi-station glue dispenser according to any of claims 1 to 10, comprising the following steps:

S1, obtaining a wafer and scanning and positioning the wafer;

S2, preheating the wafer and measuring the temperature of the wafer continuously during the preheating;

S3, transporting, when the wafer is preheated to a first set temperature, the wafer to a glue dispensing station to perform heating; and

S4, dispensing glue onto the wafer when the wafer is heated to a second set temperature.

12. The method of claim 11, wherein in the step S4, the temperature of the wafer is detected continuously, and the wafer is continuously to be heated when the temperature of the wafer is lower than the second set temperature.